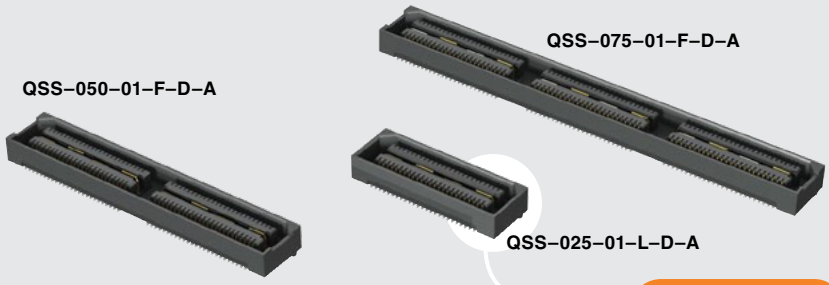
samtec

QSTRIP®



(0.635 mm) .025"

QSS SERIES

HIGH-SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QSS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
Contact: 1.8 A per pin
(2 pins powered)
Ground Plane:
23.1 A per ground plane
(1 ground plane powered)
Operating Temp:
-55 °C to +125 °C
Voltage Rating:
285 VAC
Max Cycles:
100
RoHS Compliant:
Yes

PROCESSING

Lead–Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (025-050)
(0.15 mm) .006" max (075)
Board Stacking:
For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

ALSO AVAILABLE
(MOQ Required)

- 11 mm & 16 mm stack height
- 30 µ" (0.76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount
- –LS2 Locking screw hole for QTS–RA–LS2

Contact Samtec.

Note:
Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QTS

Cable Mates:
SQCD

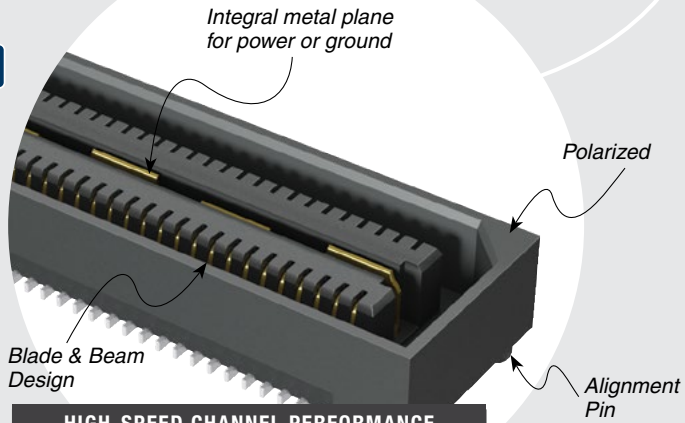
Standoffs:
SO

10 YEAR MFG WITH 50 µ" GOLD
EXTENDED LIFE PRODUCT
HIGH MATING CYCLES

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions



HIGH-SPEED CHANNEL PERFORMANCE

QSS/QTS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

25 Gbps

QSS – NO. OF POSITIONS PER ROW – 01 – PLATING OPTION – D – A – OTHER OPTION

–025, –050, –075
(50 total positions per bank)

–F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

–L
= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

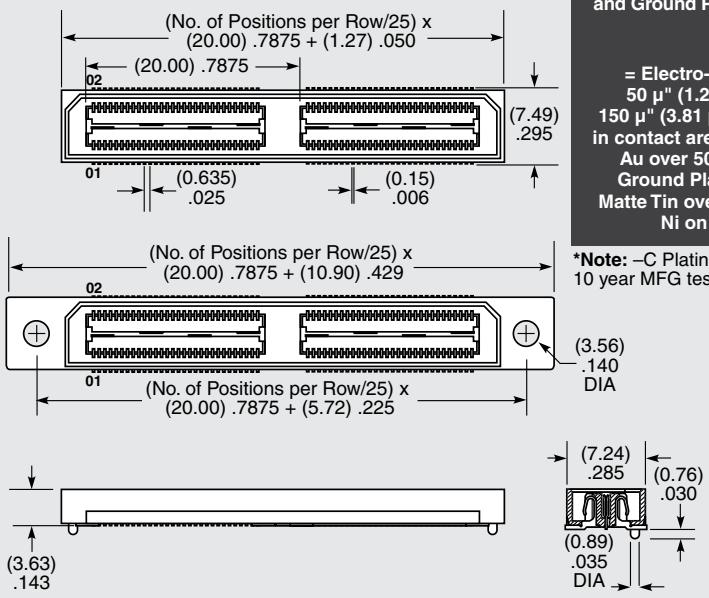
–C*
= Electro-Polished Selective 50 µ" (1.27 µm) min Au over 150 µ" (3.81 µm) Ni on Signal Pins in contact area, 10 µ" (0.25 µm) min Au over 50 µ" (1.27 µm) Ni on Ground Plane in contact area, Matte Tin over 50 µ" (1.27 µm) min Ni on all solder tails

–GP
= Guide Holes for mating with QTS-RA

–K
= (8.25 mm) .325" DIA Polyimide Film Pick & Place Pad

–TR
= Tape & Reel

***Note:** –C Plating passes 10 year MFG testing



QTS LEAD STYLE	MATED HEIGHT WITH QSS
–01	(5.00) .197
–02	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances

Due to technical progress, all designs, specifications and components are subject to change without notice.

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.